

8030

FULLY AUTOMATIC 12" TWIN



ADT 8030 Dicing system has two facing spindles that can simultaneously dice wafers at high throughput. ADT 8030 is a high accuracy system that can dice product up to 12" in diameter or 12" × 12" product, at high performances and low cost of operation.

FEATURES & BENEFITS

- Flexibility - Supports Hub and Hubless blades up to 3" O.D.
- Spindles of 1.8 kW or 2.2 kW high power
- Bridge type frame supporting efficient wafer processing
- Intuitive operation interface using a large 19" touch screen monitor
- Fast & simple blade change with a locking spindle shaft
- SECS / GEM platform ready

Specifications	8030
Workpiece Size	Ø 8", Ø 12" or 12" × 12" Square
Spindle	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm
Blade Size	2" - 3"
Y1 / Y2 Axis, Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
Cutting range	350 mm
X Axis	Air Slide
Z1 / Z2 Axis, Resolution	0.2 µm
Repeatability	1.0 µm
Max. stroke	50 mm (for 2.188" blade OD)
θ Axis, Repeatability	4 arc-sec
Stroke	380°
Cleaning Station	Full rinse and dry cycle
Spinning speed	100-3,000 rpm
Cleaning Method	Atomized cleaning capabilities
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions (W × D × H) mm	1,145 × 1,687 × 1,830
Weight	1,500 kg

Note: Specifications are subject to change without notice.

8020

FULLY AUTOMATIC 8" TWIN



ADT 8020 Dicing system has two facing spindles that can simultaneously dice wafers at high throughput. ADT 8020 is a high accuracy system that can dice product up to 8" in diameter, at high performances and low cost of operation.

FEATURES & BENEFITS

- Flexibility - Supports Hub and Hubless blades up to 3" O.D.
- Spindles of 1.8 kW or 2.2 kW high power
- Intuitive operation interface using a large 19" touch screen monitor
- Fast & simple blade change with a locking spindle shaft
- SECS / GEM platform ready

Specifications	8020
Workpiece Size	Ø 8"
Spindle	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm
Blade Size	2" - 3"
Y1 / Y2 Axis, Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
Cutting range	210mm
X Axis	Air Slide
Z1 / Z2 Axis, Resolution	0.2 µm
Repeatability	1.0 µm
Max. stroke	30 mm (for 2.188" blade OD)
θ Axis, Repeatability	4 arc-sec
Stroke	380°
Cleaning Station	Full rinse and dry cycle
Spinning speed	100-3,000 rpm
Cleaning Method	Atomized cleaning capabilities
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions (W × D × H) mm	1,015 × 1,460 × 1,820
Weight	1,300 kg

Note: Specifications are subject to change without notice.

7900/20/30

AUTOMATIC TWIN



ADT 7900 series has two facing spindles that can simultaneously dice wafers or packages at high throughput. ADT 7900 series is a high accuracy system that can dice product at high performances and low cost of operation.

Basic machine models:

- 7900 Duo support Ø 8"
- 7920 Duo up to 10" × 10"
- 7930 Duo up to 12" × 10" or Ø 12"

FEATURES & BENEFITS

- Fast & Simple Blade Change
- SECS/GEM platform ready
- Full access to any area of the system for easy maintenance
- Air bearing feed axis (X)
- Fast automatic alignment and cut positioning for increased throughput

Specifications	7900 Duo	7920 Duo	7930 Duo
Workpiece Size	Ø 8"	10" × 10"	12" × 10" or Ø 12"
Spindle	Two facing 1.8 kW or 2.2 kW shaft lock spindles, max. 60,000 rpm		
Blade Size	2" - 3"		
Y1 / Y2 Axis, Control	Linear encoder for each Y axis		
Resolution	0.1 µm		
Cumulative Accuracy	1.5 µm		
Indexing Accuracy	1.0 µm		
X Axis	Air Slide		
Z1 / Z2 Axis, Resolution	0.2 µm		
Repeatability	1.0 µm		
Stroke	30 mm (for 2.188" blade OD)		
θ Axis, Repeatability	4 arc-sec		
Stroke	350°		
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase		
Dimensions (W × D × H) mm	875 × 975 × 1450		
Weight	900 kg		

Note: Specifications are subject to change without notice.



DICING EQUIPMENT



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71xx 2" AND 4" SPINDLE DICING SYSTEM



The 7120 / 7130 families of 2” and 4” spindle dicing systems deliver a high level of affordability and flexibility to support your needs.

FEATURES & BENEFITS

- Support 2"-3" and 4"-5" blade O.D. with large 'Z' stroke
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution
- Fast & simple blade change with a locking spindle shaft (for 2” spindle)

Specifications	7122	7124	7132	7134
Workpiece Size	Ø 8"		Ø 12" or 300mm × 300mm W/O frame	
Spindle	60K rpm / 1.8 kW	30K rpm / 2.5 kW	60K rpm / 1.8 kW	30K rpm / 2.5 kW
Blade Size	2" - 3"	4" - 5"	2" - 3"	4" - 5"
Y Axis, Control	Linear encoder for each Y axis			
Resolution	0.1 µm			
Cumulative Accuracy	1.5 µm			
Indexing Accuracy	1.0 µm			
X Axis	Air Slide			
Z Axis, Resolution	0.2 µm			
Repeatability	1.0 µm			
θ Axis, Repeatability	4 arc-sec			
Stroke	350°			
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase			
Dimensions (W × D × H) mm	965 × 1300 × 1600			
Weight	900 kg			

Note: Specifications are subject to change without notice.

*** Special 7100 XLA available with 2" and 4" spindle covering 24" × 18"**

71MD 2" DICING SYSTEM FOR MEDICAL



The 71MD dicing system is designed for demanding and tight applications such as PZT. The system is equipped with Height on parts measuring system and it can be provided with large Z clearance. It can also be supplied with a balancing tool to minimize spindle vibration, typical for Ultra-Sound sensors applications.

FEATURES & BENEFITS

- Multi Panel handling
- Custom Jigs
- Geometric Model Finder (GMF)
- Large Z clearance
- Low-vibration spindle
- High resolution water flow coolant
- Z Linear encoder
- Height Measuring Tool (HMT)

Specifications	71MD
Workpiece Size	Ø 8"
Spindle	60K rpm / 1.8 kW
Blade Size	2" - 3"
Features	Z Linear encoder Z Clearance Height on parts GMF - Geometrical Model Finder
Y Axis, Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
X Axis	Air Slide
Z Axis, Resolution	0.2 µm
Repeatability	1.0 µm
θ Axis, Repeatability	4 arc-sec
Stroke	350°
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions (W × D × H) mm	965 × 1300 × 1600
Weight	900 kg

Note: Specifications are subject to change without notice.

71TS 2" TILTED SPINDLE



The Tilting Spindle dicing system is designed to meet the needs of Optoelectronic component manufacturers by providing both perpendicular cuts and 8° angular cuts needed to suppress back-reflection in fiber optic components. The system offers quick changeover from perpendicular (0°) to any angle up to 15°.

TYPICAL APPLICATIONS

- Silicon, Silica-on Silicon
- InP
- Fiber Wave Guides
- Fused Silica
- Polymers on Si
- GaAs
- LiNbO3

Specifications	71TS
Workpiece Size	Ø 8"
Spindle	60K rpm / 1.8 kW
Blade Size	2" - 3"
Features	Two preset angles: - First angle at 0° - Second angle at 0° C-15° - Fine angle adjust capability
Y Axis, Control	Linear encoder for each Y axis
Resolution	0.1 µm
Cumulative Accuracy	1.5 µm
Indexing Accuracy	1.0 µm
X Axis	Air Slide
Z Axis, Resolution	0.2 µm
Repeatability	1.0 µm
θ Axis, Repeatability	4 arc-sec
Stroke	350°
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions (W × D × H) mm	965 × 1300 × 1600
Weight	900 kg

Note: Specifications are subject to change without notice.

72xx FULLY AUTOMATIC DICING SYSTEM



The 7200 system offers a wide range of advanced automation and process monitoring option to meet the throughput and quality requirements of your most challenging dicing applications: silicon, glass on silicon, BGA & QFN packages, LTCC, ceramic, PCB and other hard material applications.

FEATURES & BENEFITS

- Efficient wafer handling system
- Continuous digital magnifications vision system
- Blade wear prediction algorithm reduces height measurement time and increases UPH
- Atomized wafer cleaning technology for superior process results

Specifications	7222	7223	7224	7200-300 2"	7200-300 4"
Workpiece Size	Ø 8"			Ø 12" or 253mm × 243mm	
Spindle	60K rpm / 1.8 kW		30K rpm / 2.5 kW	60K rpm / 1.8 kW	30K rpm / 2.5 kW
Blade Size	2" - 3"		4" - 5"	2" - 3"	4" - 5"
Y Axis, Control	Linear encoder for each Y axis				
Resolution	0.1 µm				
Cumulative Accuracy	1.5 µm				
Indexing Accuracy	1.0 µm				
X Axis	Air Slide				
Z Axis, Resolution	0.2 µm				
Repeatability	1.0 µm				
θ Axis, Repeatability	4 arc-sec				
Stroke	350°				
Cleaning Station	Full rinse and dry cycle				
Spinning speed	100-2,000 rpm				
Cleaning Method	Atomized cleaning capabilities				
Utilities, Electrical	200-240 VAC, 50/60 Hz, single phase				
Dimensions (W × D × H) mm	965 × 1460 × 1700			1100 × 1785 × 1700	
Weight	1,200 kg			1,350 kg	

Note: Specifications are subject to change without notice.